

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

TAKATA et al.

Art Unit: Unknown

Application No.: Unknown

Examiner: Unknown

Filed: March 15, 2001

For: SEMICONDUCTOR
PACKAGE

#4/Pre.
a
marsh
2/4/02

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Prior to the examination of the above-identified patent application, please enter the following amendments and consider the following remarks.

IN THE SPECIFICATION: ✓

Replace the paragraph beginning at page 2, line 24 with:

a' The sealing using a resin is carried out using a mold, and the semiconductor package is pushed out of the mold using eject pins. When eject pin receiving portions 8 of the sealing resin shown in Fig. 16 are pushed up by the eject pins (not shown) so as to remove the semiconductor package from the mold, stress on the semiconductor chip is increased if the section modulus is reduced. Moreover, since the size of semiconductor chips is being reduced from year to year, resulting in a greater reduction in the sectional modulus and an increasing stress is applied to the semiconductor chip.

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